FTA300 Anodic Wafer Bonder System

[FEATURES]

- MEMS application, R&D
- 4~12inch wafer manual loading
- High voltage : 100~1000VDC
- High vacuum : < $5x10^{-6}$ Torr (Rotary + Turbo pump)
  * 상온, 1시간 pumpin시 예상
  * Turbo pump ultimate pressure : $7.5x10^{-8}$ Torr
- High pressure : upto 8,000N
- High Temperature : process at ~370℃
- Self flatness alignment : prevent wafer damage

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